STATES PATENT AND TRADEMARK OFFICE

In re Application of

Tomohide TERASHIMA

Serial No.: 09/834,954

Filed: April 16, 2001

For:

SEMICONDUCTOR DEVICE

Group Art Unit: 2826

Examiner: Johannes P. Mondt

TECHNOLOGY CENTER 2800

THE COMMISSIONER FOR PATENTS AND TRADEMARKS Washington, DC 20231

Dear Sir:

Transmitted herewith is an Amendment in the above identified application. No additional fee is required. Applicant is entitled to small entity status under 37 CFR 1.27

The fee has been calculated as shown below:

Also attached:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	12	20	0	\$18.00 =	\$0.00
Independent Claims	2	3	0	\$84.00 =	\$0.00
		Multiple claims newly presented			\$0.00
		Fee for extension of time			\$0.00
					\$0.00
		Total of Above Calculations			

Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this П transmittal sheet is submitted herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication \boxtimes or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted.

MCDERMOTT, WILL & EMERY

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Date: April 9, 2002

#6/A 4-12-02 Mollish PATENT

Docket No.: 57454-062

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Tomohide TERASHIMA

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AMENDMENT

Box Non-Fee Amendment The Commissioner for Patents and Trademarks Washington, DC 20231

Sir:

The following Amendment and Remarks are submitted in response to the Office Action dated January 9, 2002. Please amend the above-identified application as follows:

IN THE CLAIMS:

1. (Amended) A semiconductor device including:

a semiconductor substrate having a main surface;

a semiconductor layer of a first conductive type which is formed on the main surface of said semiconductor substrate;

a first buried impurity region of the first conductive type formed between said semiconductor layer and said semiconductor substrate;

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